

# Temperature Dependence of Dark Signal for Sentinel-4 Detector

Ralf Reulke<sup>1,2</sup>, Michael P. Skegg<sup>3</sup>, Rüdiger Hohn<sup>3</sup>

<sup>1</sup>German Aerospace Center, <sup>2</sup>HU-Berlin, <sup>3</sup>Airbus Defence and Space

26 November, 2019

The 5th Asian Conference on Pattern Recognition (ACPR 2019)

WS8: Data Processing Chain for Airborne and Spaceborne Sensors

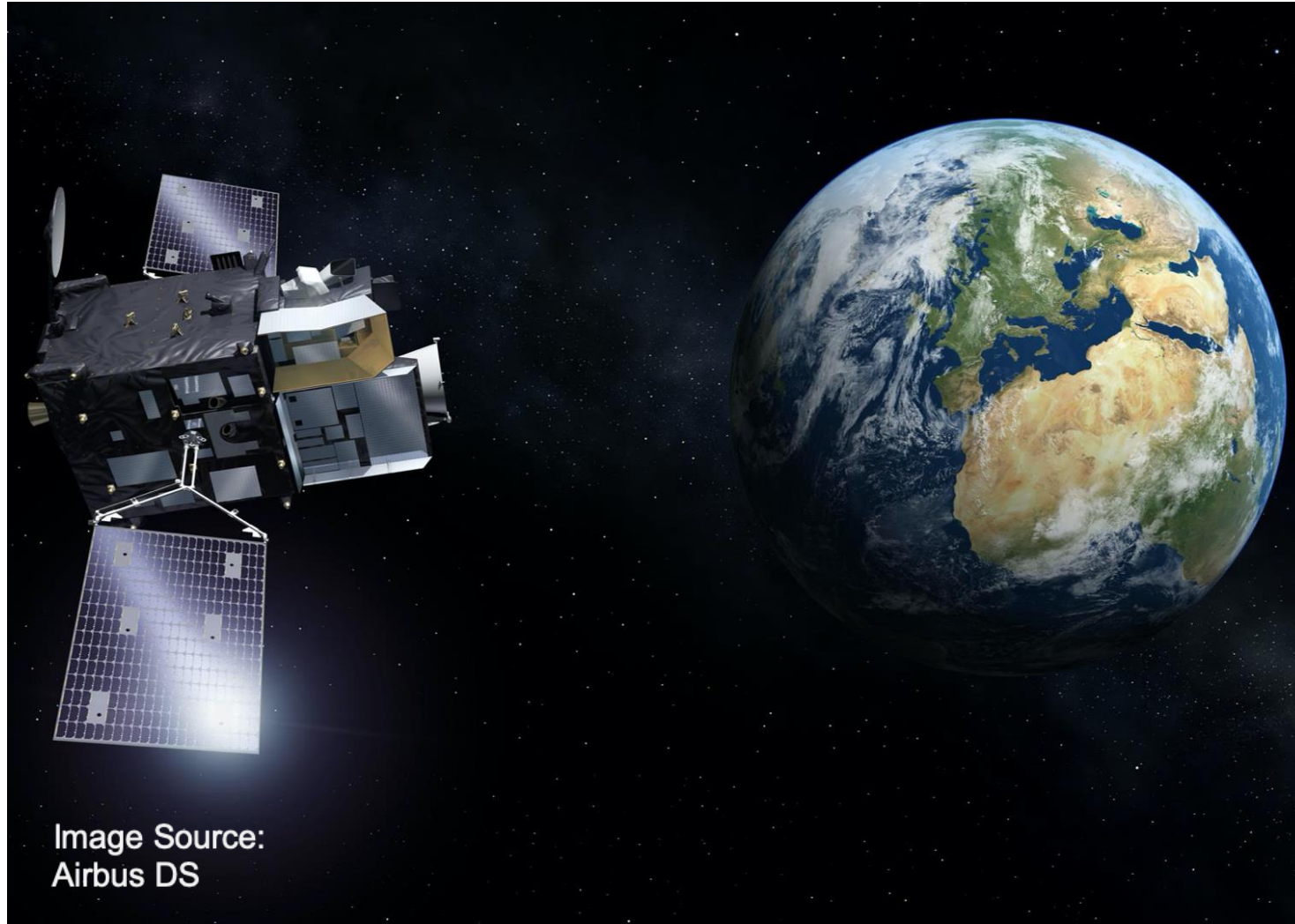
# Motivation

- Dark signal is an important parameter for sensor performance
- Has a remarkable temperature dependence
- Optimisation is an important task for scientific detector / sensor
  
- Modelling is significant for sensor design and calibration
- Modern calibration approach is based on models & measurement / recognition of deviations
  
- Dark signal measurement was done with Sentinel-4 FPA
- Model test and recognition of deviations from model behaviour

# Overview

- Senstinel-4 mission, detector, verification
- Detector Signal Model
- Dark Signal Calculation
- Measurements
- Results
- Discussion & Outlook

# Overview - Sentinel 4 Mission



- Part of ESA's COPERNICUS Program (Environmental Surveillance)
- Sentinel 4 → Atmospheric Surveillance
- Hyperspectral Instrument with 2 detectors:
  - UVVIS (305 nm ... 500 nm)
  - NIR (750 nm ... 775 nm)
- Geostationary orbit above Europe
- East-West Scan in frequency of 1h

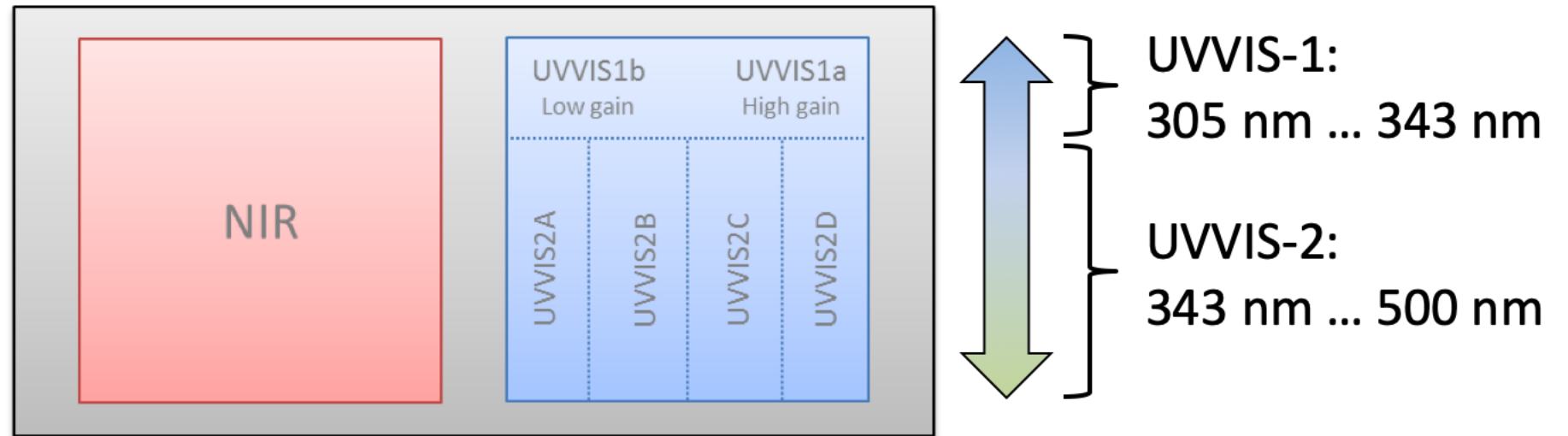
# Sentinel 4 QM Verification Campaign @DLR Berlin

- Verification of Opto-Electronic Payload
- First “Marriage” of FPAs and Front End Electronics after Manufacturing
- Challenging of Opto-Mechanical Boundaries
  
- Deployment of Thermal Vacuum Chamber (TVC):
- Operating Temperature of Detectors / FPAs = 215 K +/- 5 K
- AR-layers on detectors (without cover glass)
  - Sensitive + Hygroscopic

## Detector Design

“Simple” AR-coating on NIR

Graded AR-coating on UVVIS

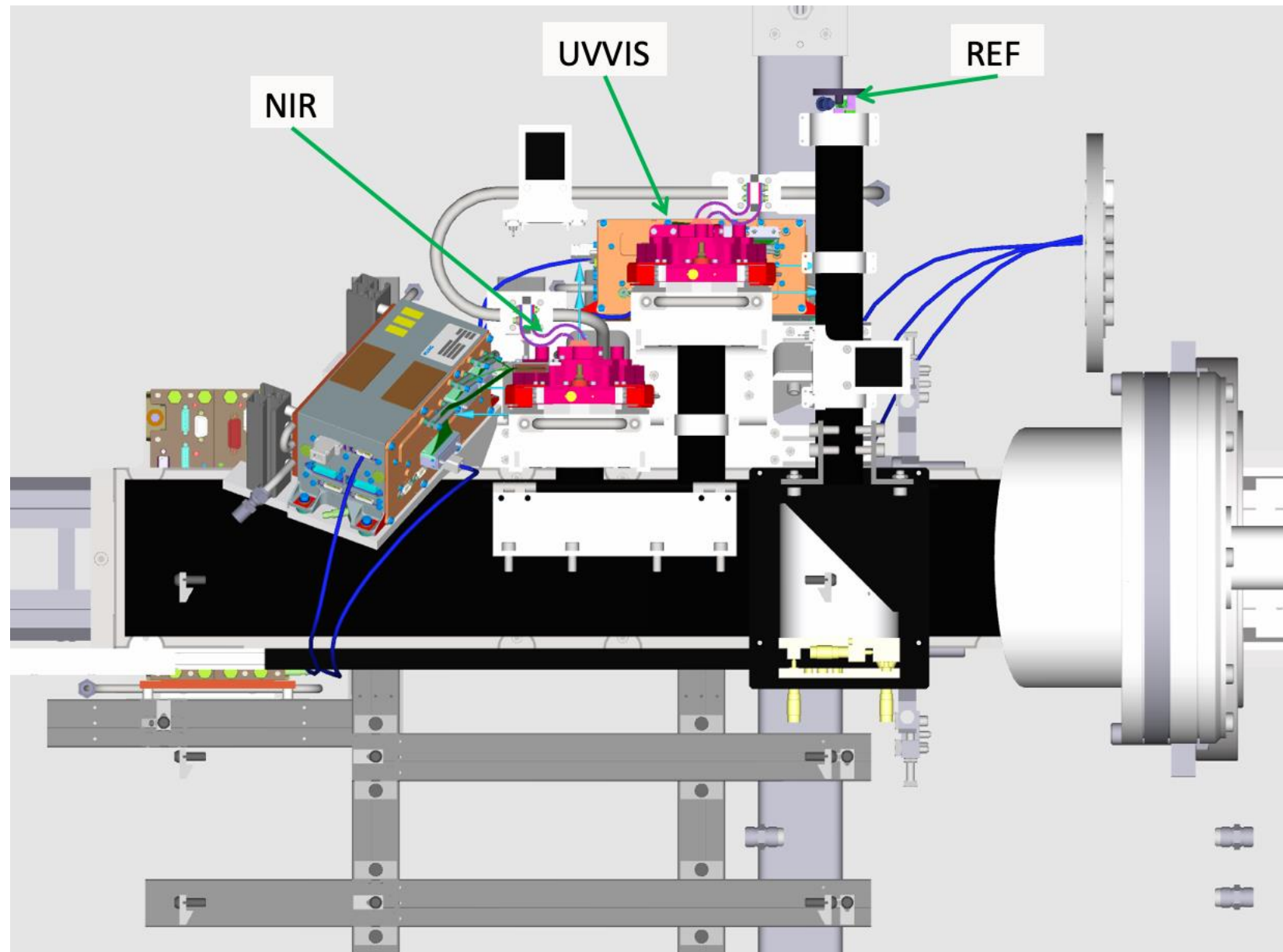


Sentinel-4 detector design of NIR and UV-VIS detector.

- Single point read out on NIR detector
- Separated read-out regimes on UV-VIS detector for
  - Gain adjustment (UVVIS 1)
  - Faster read out (UVVIS 2)

# Measurement Setup

- Equal optical path lengths for REF-, UVVIS-, NIR-detector
- Remote flat field illumination via integrating sphere + filters (Spectr./ND)
- Additionally 635 nm Laser
- Pressure  $\sim 5 \cdot 10^{-6}$  mbar
- Two different temperature circuits:  
FPAs:  
210, 215, 220 K and  
273, 283, 293 K  
FEEs and FSE constantly  
293 K
- First „marriage“ of FPAs and FEEs/FSE
- Highly automated test runs



# Measurements & Results

Performed Test	Derived Analyses	Result
<b>Linearity</b>	Linearity	✓
	FPS gain / conversion factor	✓
	Full Well Capacity (linear)	✓
	Full Well Capacity (absolut)	✓
	Signal to Noise Ratio	✓
	Charge Transfer Efficiency (Serial)	✓
	Charge Transfer Efficiency (Parallel)	✓
	<b>Average Dark Signal</b>	Average Dark Signal
Dark Signal Non-Uniformity		✓
Read-out Noise		✓
Dynamic Range		✓
<b>Memory Effect</b>	Memory Effect	✓
<b>Cross –Talk</b>	Channel to Channel Cross Talk	✓
<b>Stability over 24 h</b>	Stability over 24 h	✓
<b>Random Telegraph Signal</b>	RTS and pixels with high dark noise	✓
<b>FPA LED Calibration</b>	FPA LED Calibration	✓
<b>Quantum Efficiency</b>	QE	✓ (verification of e2v test)
<b>Photo Response Defects</b>	Photo Response Defects	✓ (surface fit correction)
	Photo Response Non-Uniformity	✓ (surface fit correction)



## Detector Signal Model for the Average Signal

$$\langle s \rangle = \eta_{DV} \cdot \eta_V \cdot \eta_{\lambda}^{qu} \cdot \tau \cdot A_{pix} \cdot \frac{\lambda}{hc} \cdot E + DS$$

$\langle s \rangle$	Camera output signal [DN]
$h$	Plank's constant [Js]
$c$	Speed of light [m/s]
$\lambda$	Center wavelength of incident light [m]
$G_S = \eta_{DV} \cdot \eta_V$	Overall system gain [DN/e <sup>-</sup> ]
$E$	Irradiance at detector level [W/m <sup>2</sup> ]
$\tau_{int}$	Integration time [s]
$A_{pix}$	Pixel area [m <sup>2</sup> ]
$DS$	Dark signal [DN]

- Three noise-components:
  - photon noise,
  - dark current noise, and
  - read-noise.
- Photon and dark current noise are Poisson distributed.

$$\sigma_s^2 = \eta_{DV}^2 \cdot \eta_V^2 \cdot (\langle n_{el} \rangle + \langle n_{el}^D \rangle) + \eta_{DV}^2 \cdot \sigma_k^2.$$

- Or

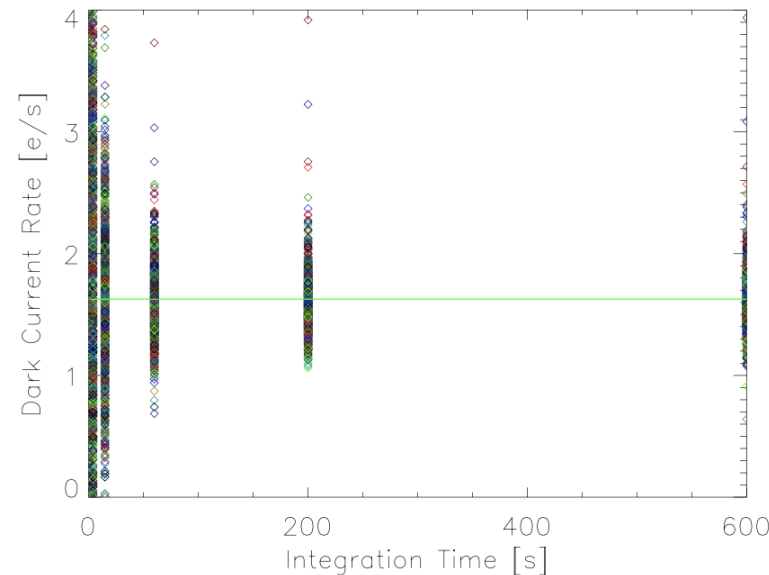
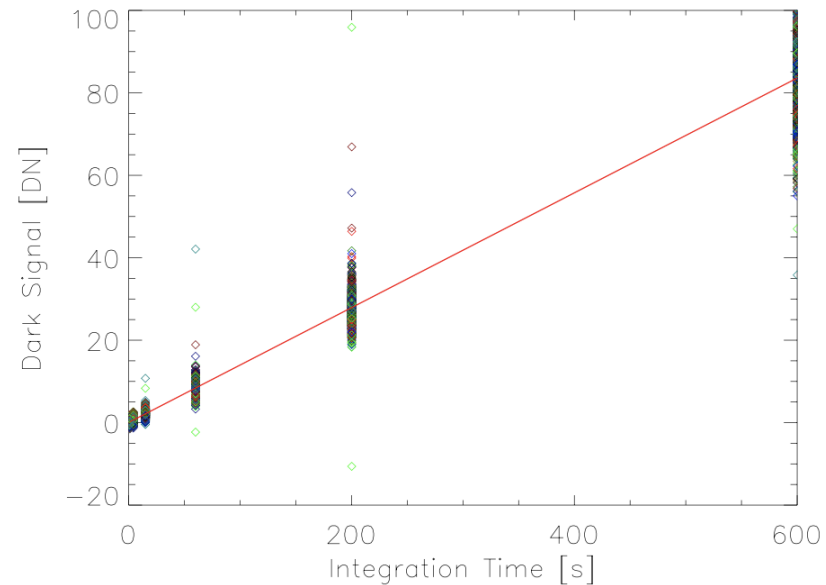
$$\sigma_s^2 = G_S \cdot \langle s \rangle + \eta_{DV}^2 \cdot \sigma_k^2$$

- This linear equation is a relation between variance of measured noise and averaged signal (**PTC -- Photon Transfer Curve**).

# Dark Signal Calculation

- Variation of dark signal  $D = G_S \cdot \langle n_{el}^D \rangle$  by either the integration time or the operating temperature ( $\rightarrow$  PTC!)
- Slope of dark signal dependence as a function of integration time

$\sigma_D^2 = D$	Variance of the dark signal
$D = \tau_{int} \cdot D_R$	Dark signal depends from
$\tau_{int}$	integration time in [s]
$D_R$	average dark current rate [e/s]



$$D_R [nA/cm^2] = 10^9 \cdot (Q \cdot D_R [e/s]) / A_{pix}$$

$$D_R [e/s] = D_R [nA/cm^2] \cdot 10^{-9} \frac{A_{pix}}{Q}$$

# Temperature Dependence of the Dark Current Rate

Model from Janesick

$$D_R = 2.55 \times 10^{15} A_{pix} \cdot D_{FM} \cdot T^{1.5} \cdot e^{-E_g/2kT}$$

Empirical model from Skegg

$$D_R = D_{FM}^* \cdot T^3 \cdot e^{-6400/T} \quad \text{with} \quad D_{FM}^* = D_R(T = 300K)$$

$$A_{pix} = 27.5 \cdot 10^{-4} \times 15 \cdot 10^{-4}$$

$D_{FM}$

$$E_g = 1.1557 - \frac{7.021 \times 10^{-4} T^2}{1108 + T}$$

$$k = 8.6173324 \times 10^{-5}$$

$$Q = 1.602176565 \times 10^{-19}$$

Pixel area [ $cm^2$ ]

DC figure-of-merit @300K in [ $e/s$ ] or [ $nA/cm^2$ ]

Silicon bandgap energy [ $eV$ ]

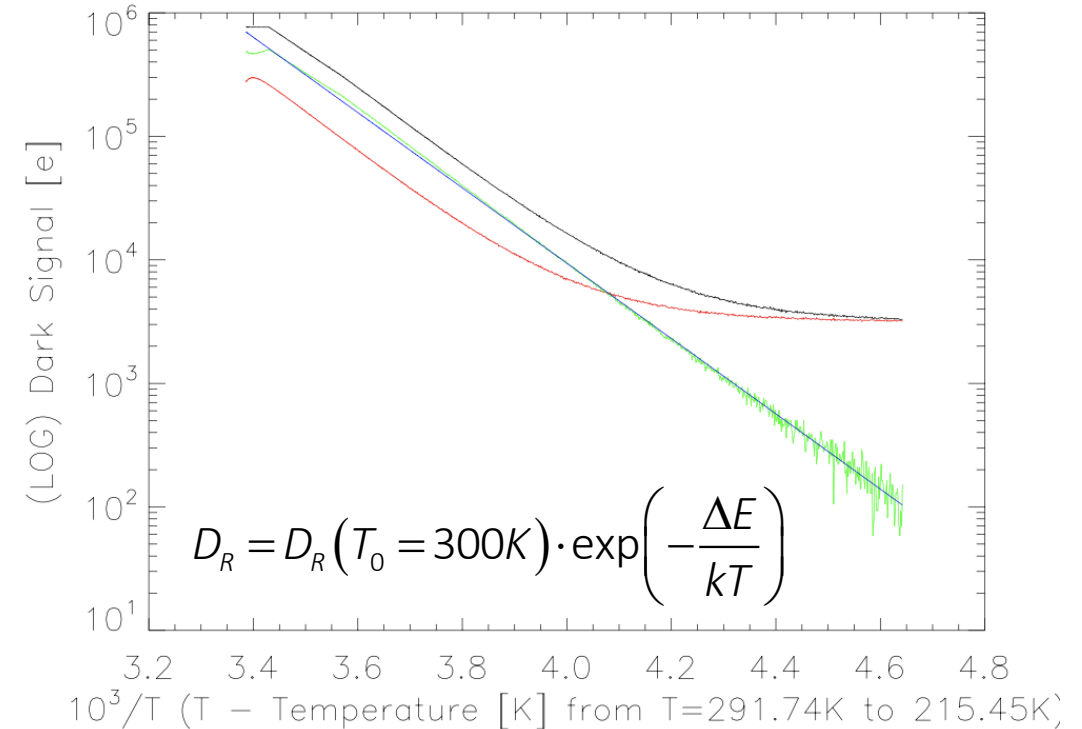
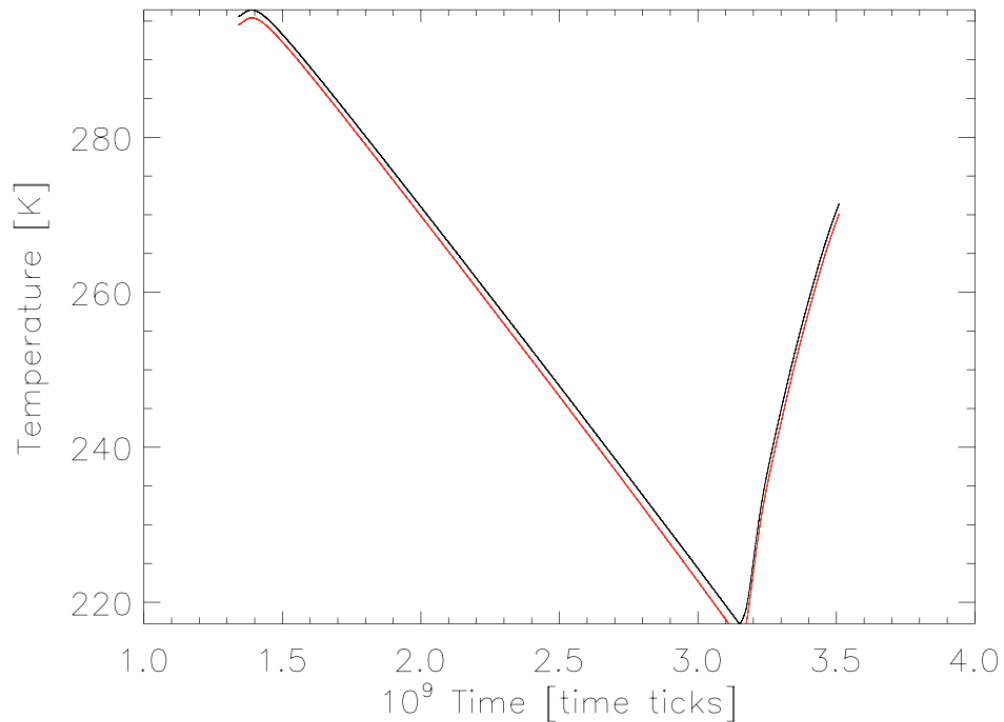
Boltzmann's constant [ $eV/K$ ]

elementary charge [ $C$ ] = [ $As$ ]

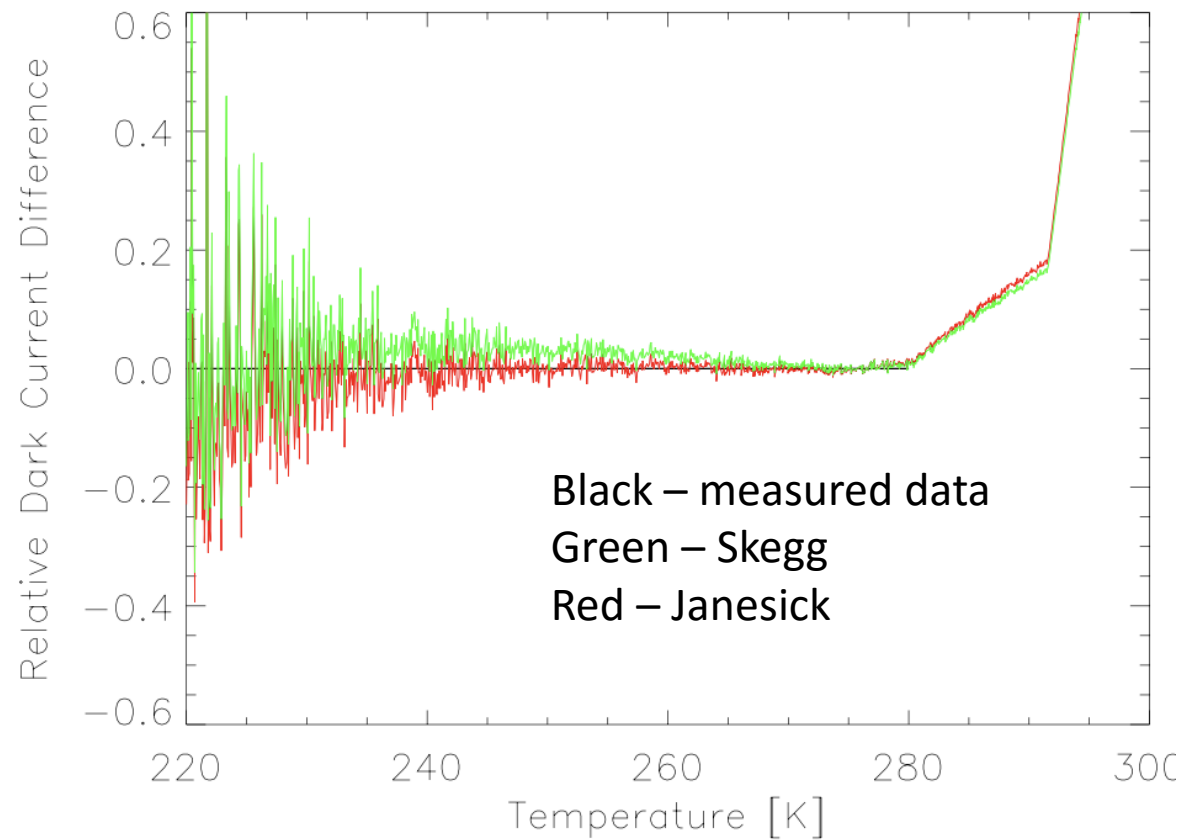
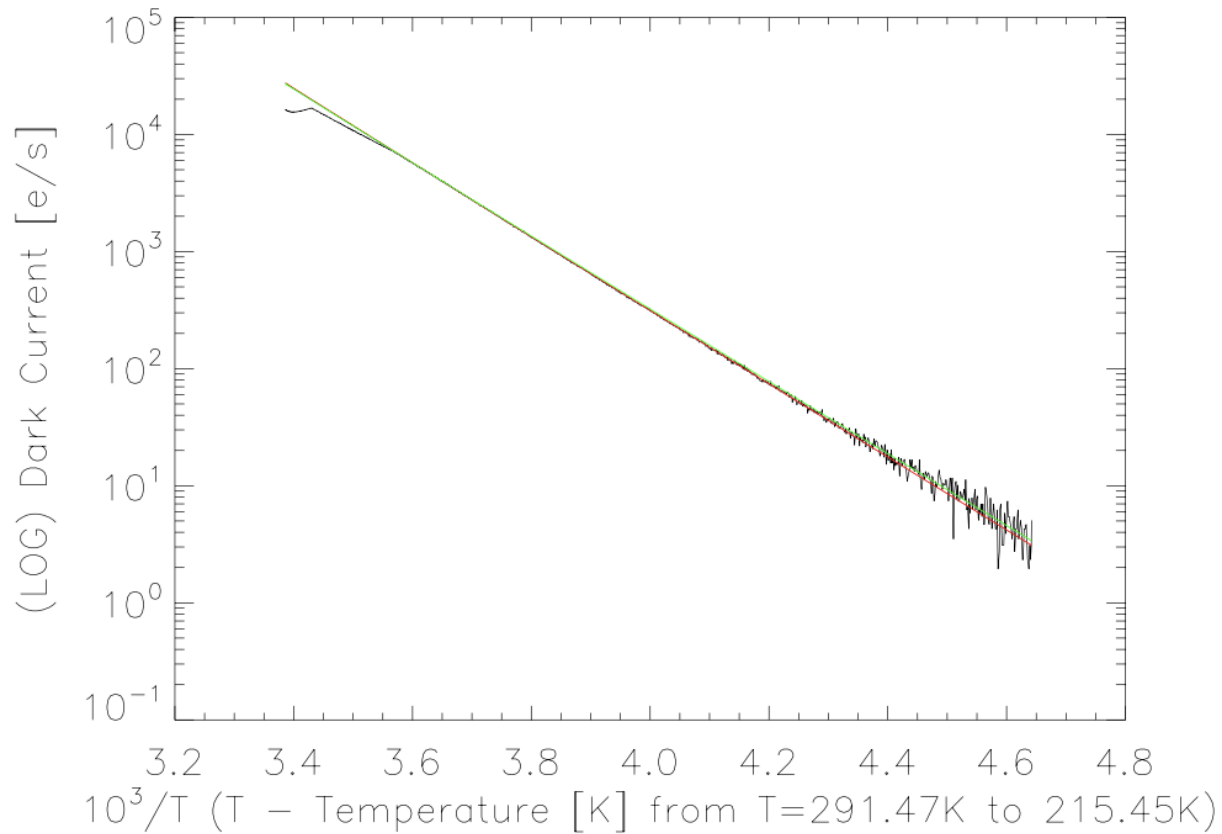
- Measurements of the dark current with an integration time of  $\tau_{int} = 30s$
- Continuous cooling from 293 K to 215 K over a period of 12 hours
- After 10 hour cooling stopped and temperatures increased again
- Measurement mode was Long Dark (with separate read-out of image and store areas)
- 42.723 temperature measurements for NIR and VIS detector

# Measurements

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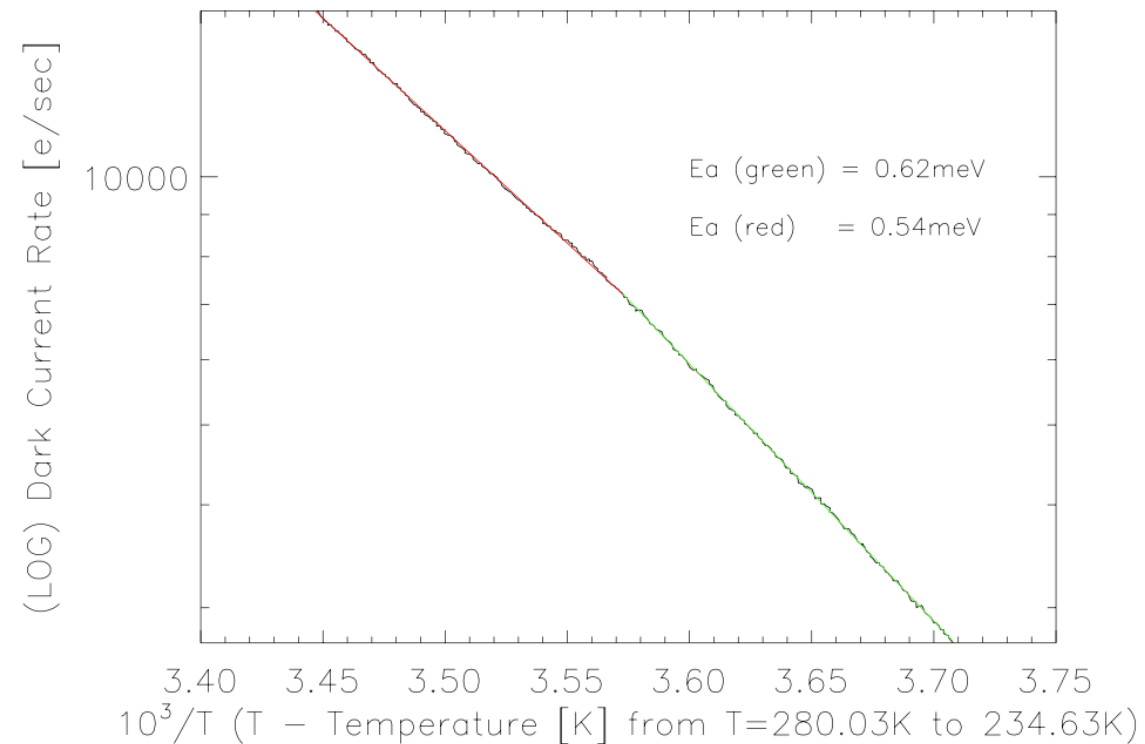
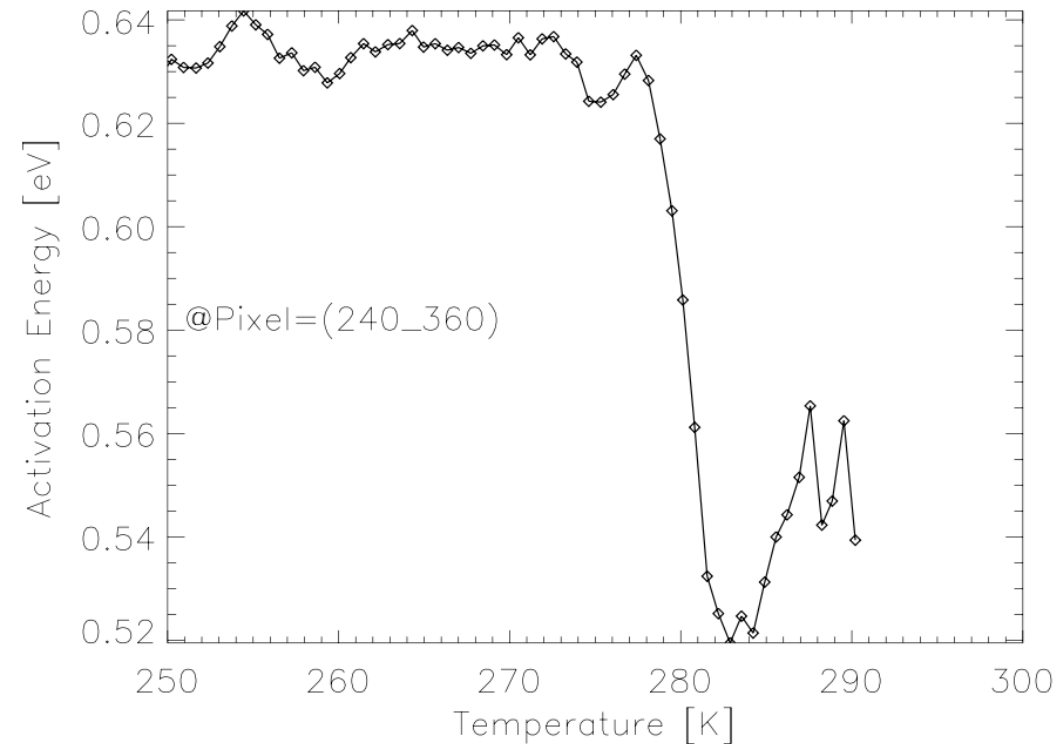


# DS - Comparison with Models



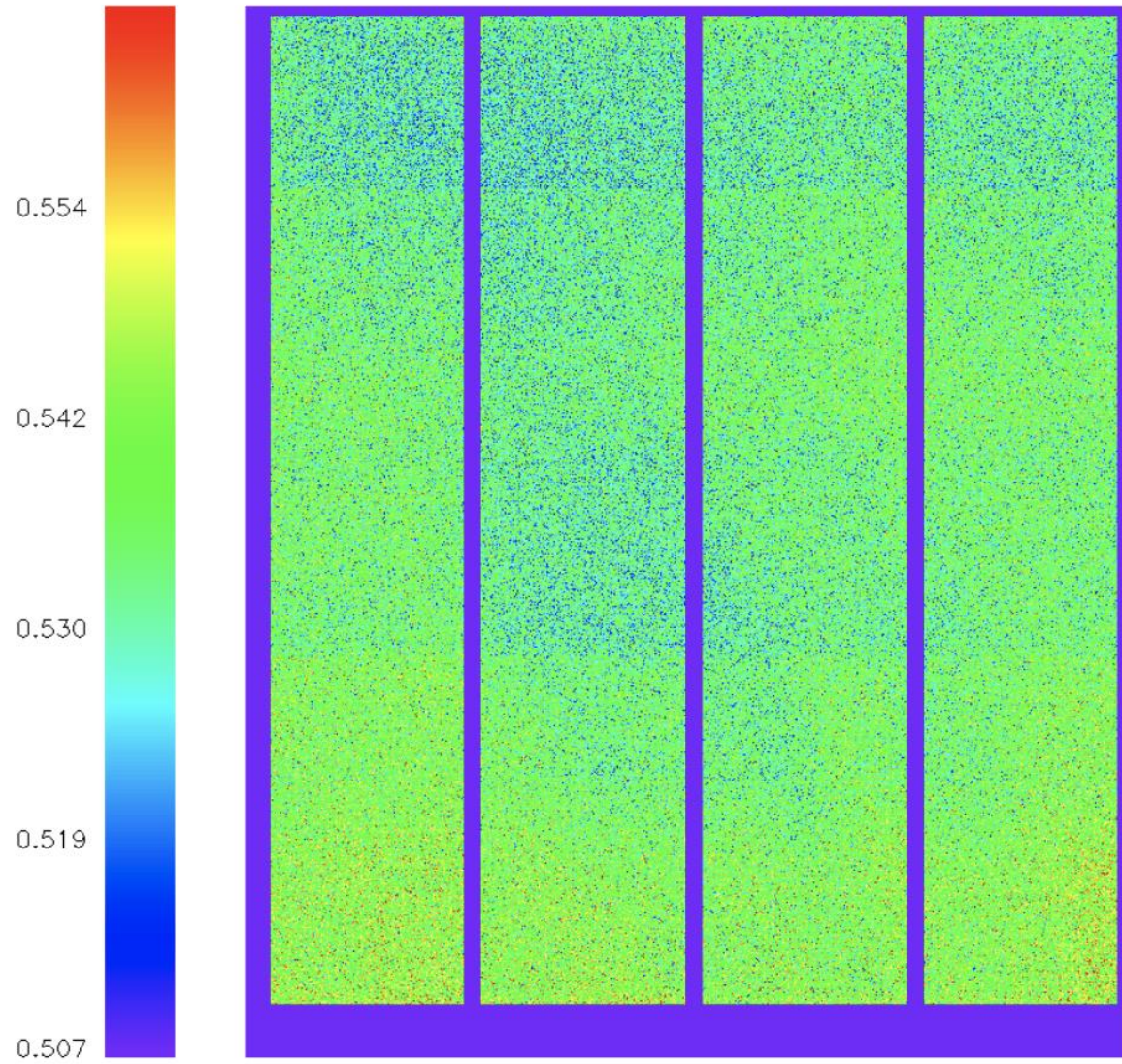
# Change of the activation Energy

NIR Temperature Dependence of the Dark Current Rate @Pixel=(240,360). Noticeable is the significant change in the activation energy at 280K

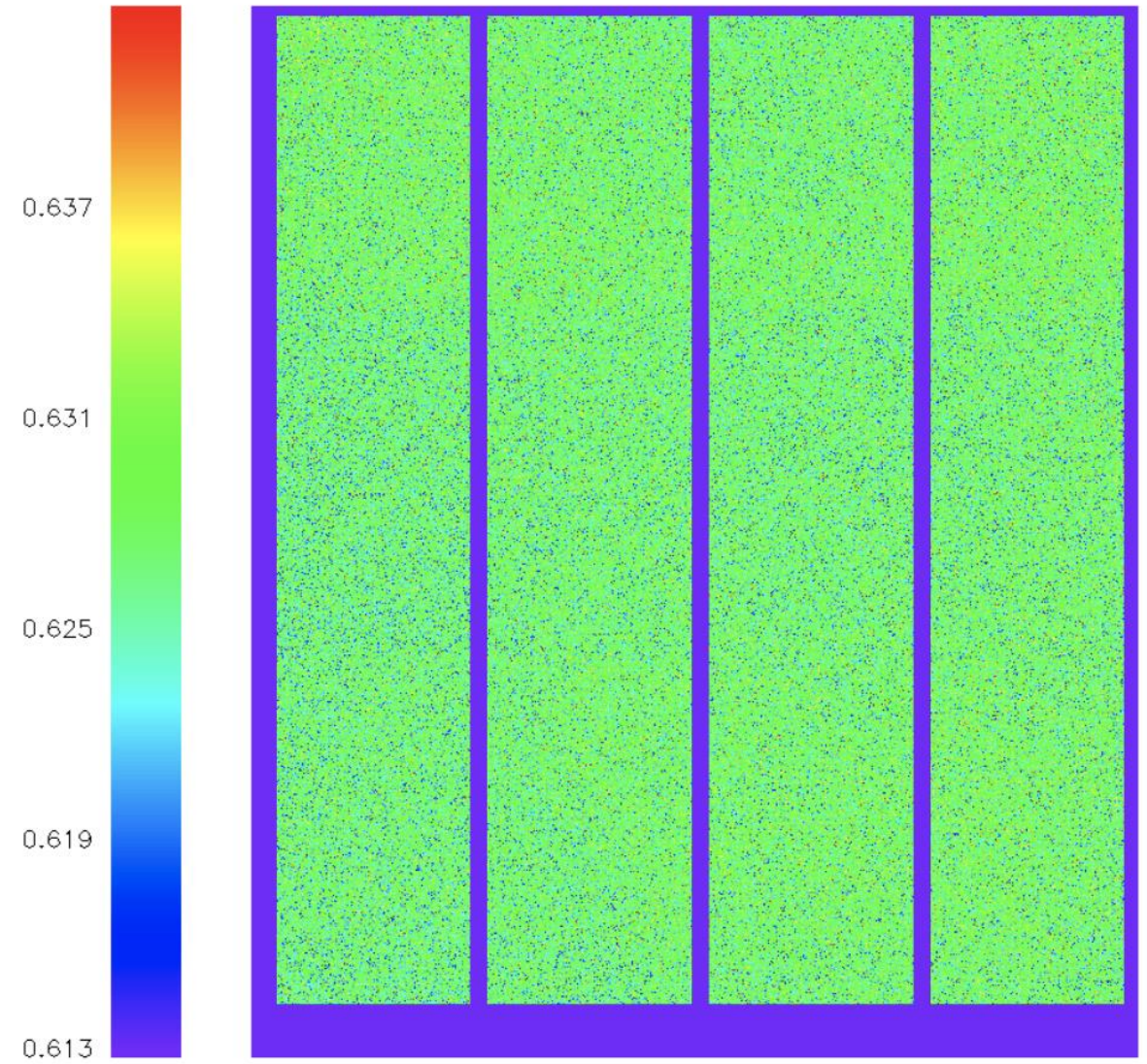




# Spatial distribution of the activation energies



26.11.19

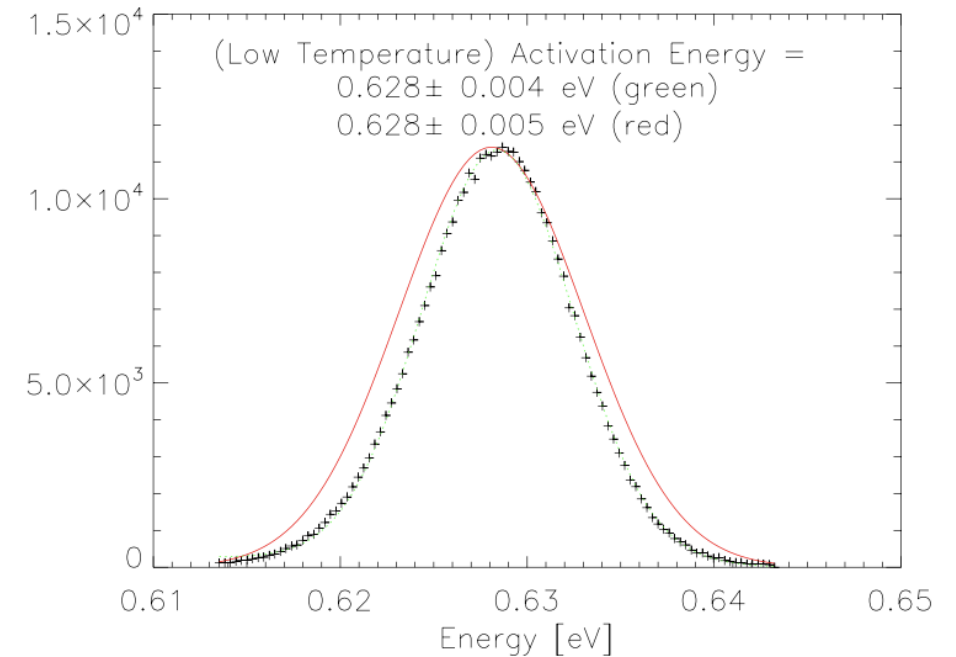
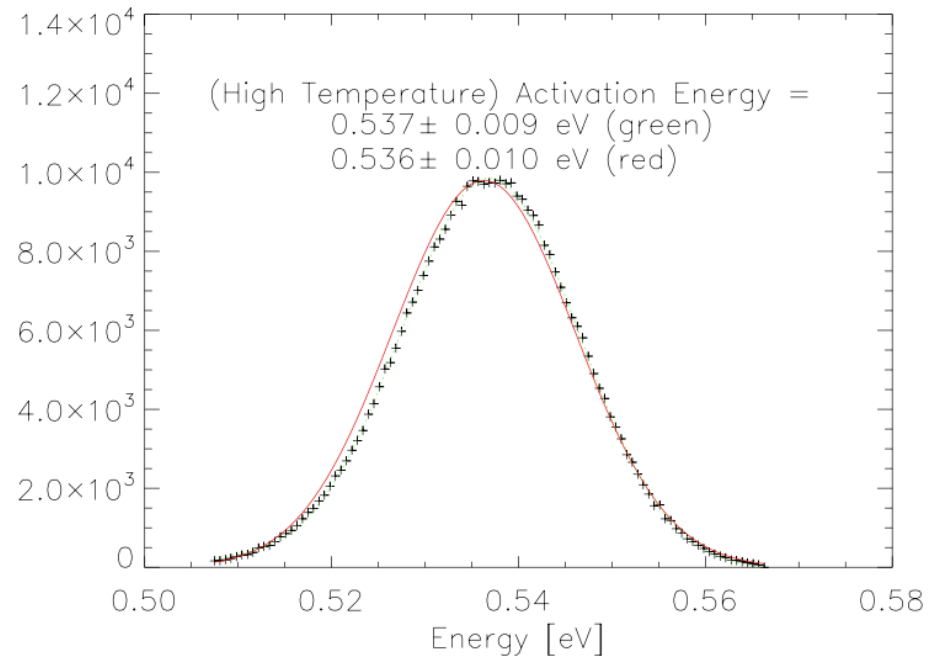


Dark Signal, Sentinel-4 Detector

15

# Histogram of the Activation Energy

Histogram values (+), in green a Gauss-fit to the histogram values, red line is the Gauss distribution derived from mean and standard-deviation of the histogram)





## Discussion & Outlook

- Investigation of temperature behaviour of the dark signal / current between 215K and 290K for a scientific CCD
- Exceptionally high number of measuring points (900 measurements with an integration time of 30s)
- Basically, the temperature behaviour of the dark current is as expected theoretically and experimentally
- Two parts of the temperature dependence of the dark - can be characterized by different activation energies
- Clear separation of the activation energies at 280K
  - Low temp activation energy =  $0.628\text{eV} \pm 0.004\text{eV}$
  - High temp activation energy =  $0.537\text{eV} \pm 0.009\text{eV}$
- The variation width for the activation energies for the entire chip was extremely small (1% -2%)

## Discussion & Outlook

- The main finding of the article is the change of the activation energy from dark current rate with the temperature
- The reason is assumed to be the changing electric field within the silicon chip, since the depletion depth decreases as the number of electrons increases
- Further measurements, which are to be carried out as part of the verification of the flight model, should deepen this knowledge